

SOT618-1

plastic thermal enhanced very thin quad flat package; no leads; 40 terminals; body 6 x 6 x 0.85 mm

8 June 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN40
Package type industry code	HVQFN40
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	22-10-2002

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		5.9	-	6	6.1	mm
E	package width		5.9	-	6	6.1	mm
A	seated height		-	-	0.85	1	mm
A ₂	package height		-	-	-	-	
e	nominal pitch		-	-	0.5	-	mm
n ₂	actual quantity of termination		-	-	40	-	

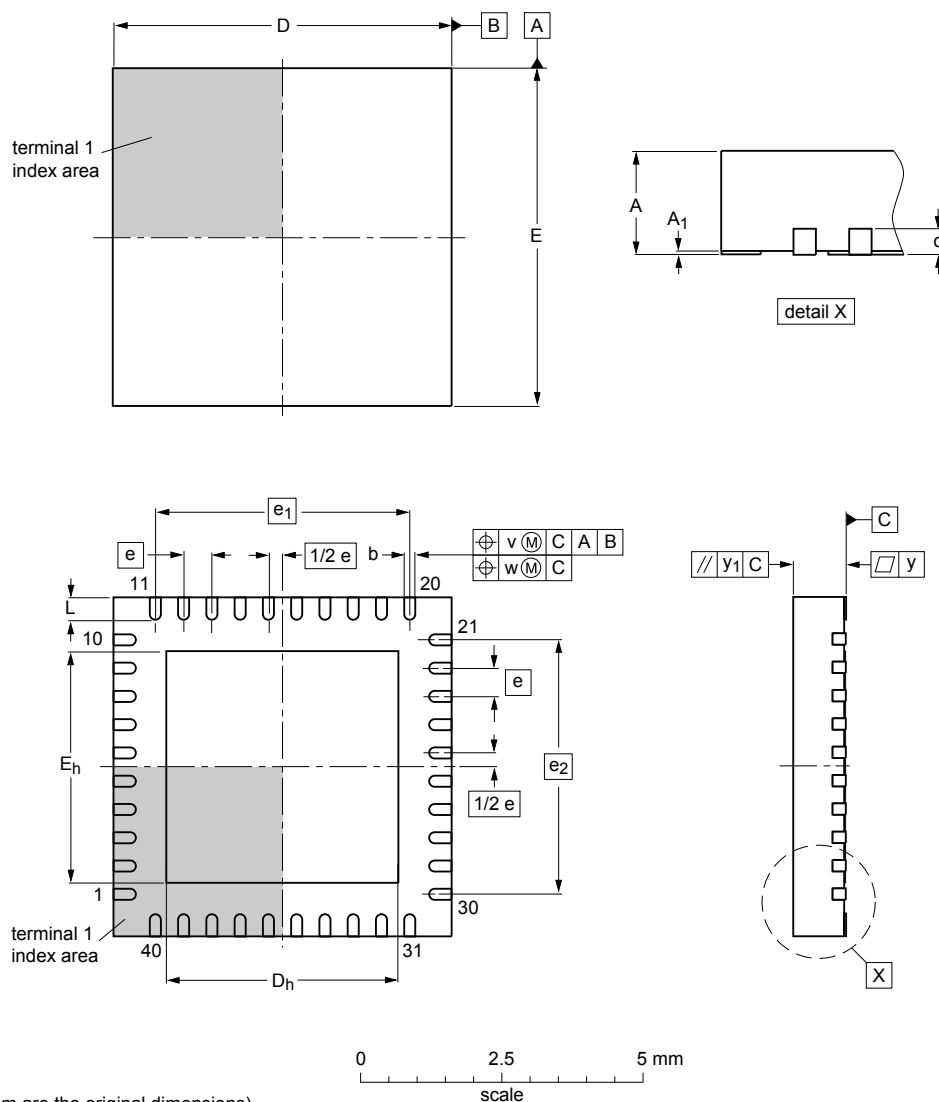


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2. Package outline

HVQFN40: plastic thermal enhanced very thin quad flat package; no leads; 40 terminals; body 6 x 6 x 0.85 mm

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Dimensions (mm are the original dimensions)

Unit		A ⁽¹⁾	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
mm	max	1.00	0.05	0.30	0.2	6.1	4.25	6.1	4.25	0.5	4.5	4.5	0.5	0.1	0.05	0.05	0.1
	nom	0.85	0.02	0.21		6.0	4.10	6.0	4.10				0.4				
	min	0.80	0.00	0.18		5.9	3.95	5.9	3.95				0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot618-1_po


Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT618-1		MO-220				02-10-22- 13-11-05

Fig. 1. Package outline HVQFN40 (SOT618-1)

3. Soldering

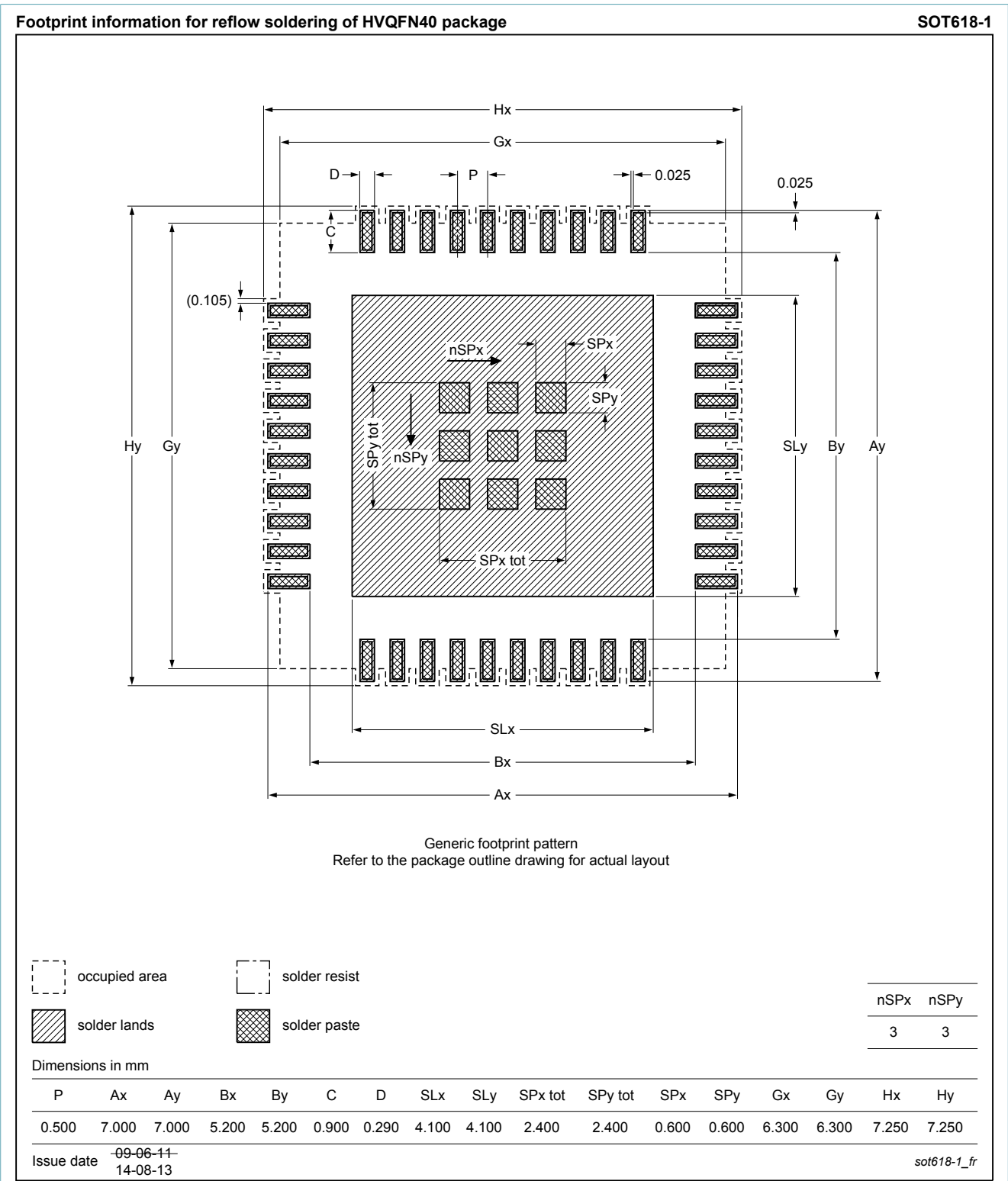


Fig. 2. Reflow soldering footprint for HVQFN40 (SOT618-1)

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4. Legal information

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